COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

SEMICONDUCTOR STRUCTURE AND FABRICATION THEREFOR

nendment referred to above. ch is material to the patentability of this legulations, § 1.56(a).	
nendment referred to above. ch is material to the patentability of this legulations, § 1.56(a).	
I hereby state that I have reviewed and understood the contents of the above-identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a). I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed: Prior Foreign Application(s):	
(s) to prosecute this application and to connected therewith:	
DIRECT TELEPHONE CALLS TO: (Name and Telephone Number)	
Belinda Lee PGroup.com.tw	
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COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature: \$ - 25 11-Ching Will Date: 6/8/2004
Sole or First Joint Inventor: Yi-Ching Wu
Citizenship: Taiwan, R.O.C.
Residence and Post Office Address: No.69-85, Bao-an Rd., Yong-an Township, Kaohsiung County 828, Taiwan R.O.C.
Signature: Date: 6/8/2004 Second Joint Inventor (if any): Jiann-Fu Chen
Citizenship: Taiwan, R.O.C.
Residence and Post Office Address: No.113, Lane 576, Sec. 1, Guangfu Rd., Hsinchu City 300, Taiwan R.O.C.
Signature: 6/8/2004 Third Joint Inventor (if any): Chih-Hsiang Shiau
Citizenship: Taiwan, R.O.C.
Residence and Post Office Address: No.20, Alley 62, Lane 99, Puding Rd., Hsinchu City 300, Taiwar

R.O.C.